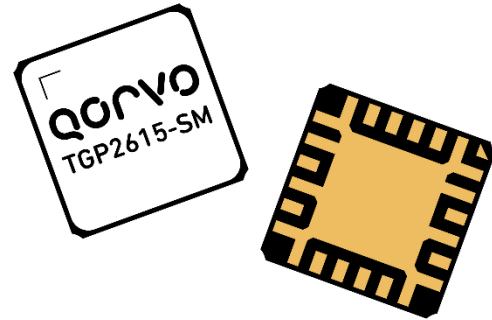


Product Description

The Qorvo TGP2615-SM is a packaged 6-bit digital phase shifter fabricated on Qorvo's high performance 0.15 um GaAs pHEMT process. It operates over 15 to 19 GHz while providing 360° of phase coverage with a LSB of 5.625°. It also achieves a low RMS phase error of 4°, with 7 dB average insertion loss over all states.

The TGP2615-SM uses positive single-control-line switch logic, eliminating the need for a negative voltage rail or complimentary logic. This, combined with low insertion loss and a high degree of resolution makes the TGP2615-SM ideally suited for applications in phased-array radar and satellite communications.

The device is lead-free and RoHS compliant.



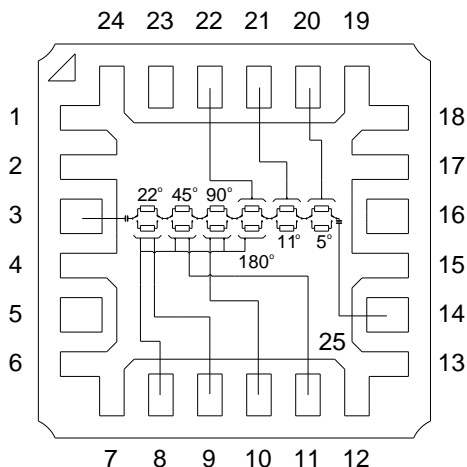
Air Cavity Ceramic QFN 4x4 mm 24L

Product Features

- Frequency Range: 15 to 19 GHz
- 6-Bit Digital Phase Shifter
- 360° Coverage, LSB = 5.625°
- RMS Phase Error: 4°
- RMS Amplitude Error: 0.85 dB
- Insertion Loss: 7 dB
- Input Return Loss: >10 dB
- Output Return Loss: >9 dB
- Input P1dB: >23 dBm
- Positive Control Logic: 0 /+3.3 V
- Package Dimensions: 4.0 x 4.0 x 1.45 mm

Performance is typical across frequency. Please reference electrical specification table and data plots for more details.

Block Diagram



Applications

- Phased-Array Radar
- Satellite Communications

Ordering Information

Part No.	Description
TGP2615-SM	15-19 GHz 6-Bit Digital Phase Shifter
TGP2615-SMEVB	TGP2615-SM EVAL BOARD



TGP2615-SM

15-19GHz 6-Bit Digital Phase Shifter

Absolute Maximum Ratings

Parameter	Value
Control and Reference Voltage	6 V
Control Current	1 mA
Power Dissipation	0.8 W
Input Power, CW, 50 Ω, 85°C	30 dBm
Channel Temperature	200 °C
Mounting Temperature (30 Seconds)	260 °C
Storage Temperature	-55 to 150 °C

Operation of this device outside the parameter ranges given above may cause permanent damage. These are stress ratings only, and functional operation of the device at these conditions is not implied. Extended application of Absolute Maximum Rating conditions may reduce device reliability.

Recommended Operating Conditions

Parameter	Value
Control Voltage (5°, 11°, 22°, 45°, 90°, 180°)	0/+3.3 V
Reference Voltage (V _{REF})	+3.3 V
Current (I _{REF} , I _{CTRL})	10 μA
Temperature Range	-40 to +85 °C

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed overall operating conditions.

Electrical Specifications

Test conditions unless otherwise noted: 25°C. Control Voltage (REF, 5°, 11°, 22°, 45°, 90°, 180°) = 0/+3.3 V; See Bias Truth Table

Parameter	Conditions	Min	Typical	Max	Units
Operational Frequency Range		15		19	GHz
Insertion Loss	Average across all phase states		6 - 8		dB
Input Return Loss	Average across all phase states		>10		dB
Output Return Loss	Average across all phase states		>9		dB
RMS Phase Error			4		deg
RMS Amplitude Error			0.85		dB
Input P1dB			>23		dBm
Insertion Loss Temperature Coefficient	Average all phase states, 19 GHz		0.002		dB/°C

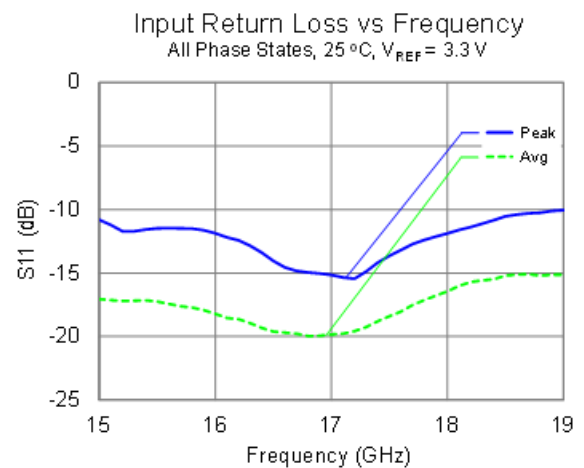
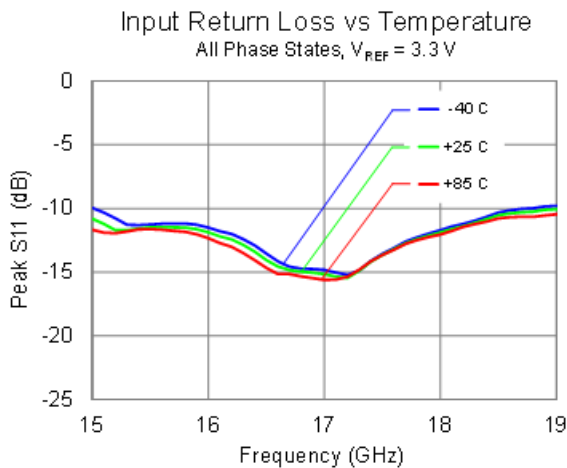
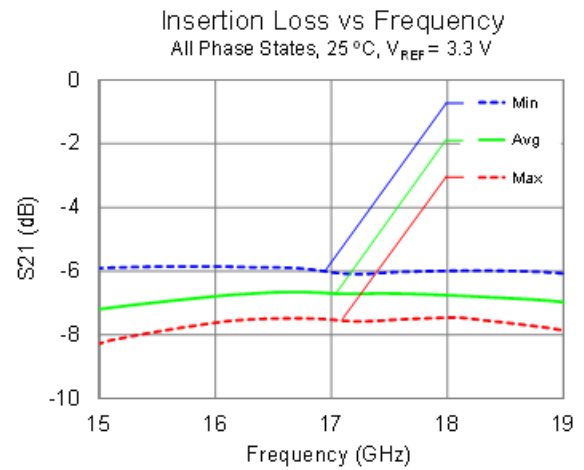
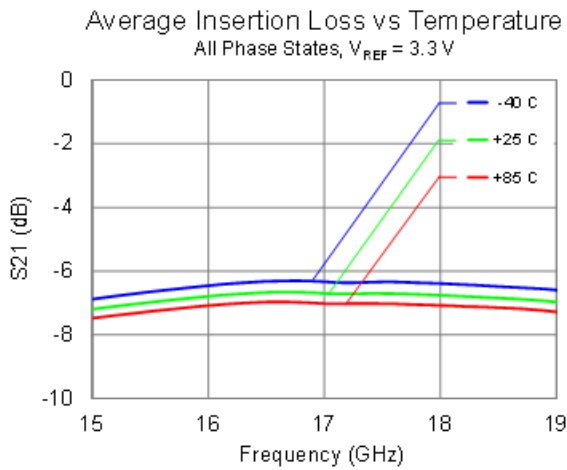
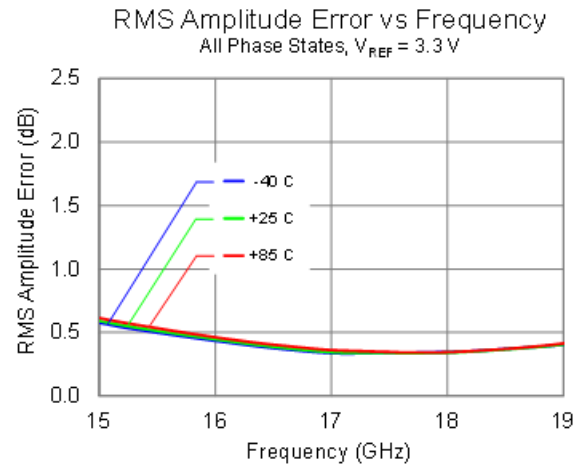
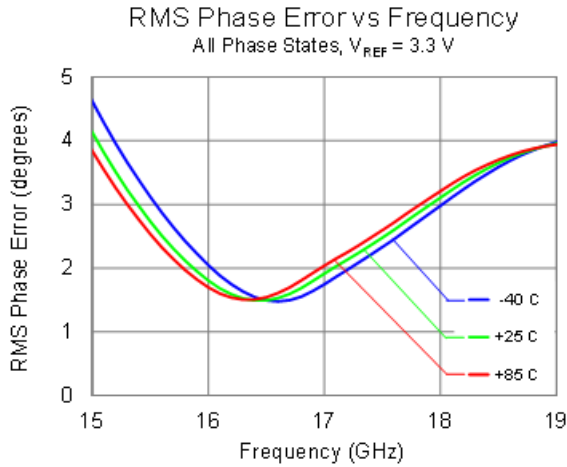
Bias Truth Table

Logic "0" = 0 V, Logic "1" = V_{REF} = +3.3 V

Phase Shifter Setting	5°	11°	22°	45°	90°	180°	REF
0° (Reference)	0	0	0	0	0	0	1
5°	1	0	0	0	0	0	1
11°	0	1	0	0	0	0	1
22°	0	0	1	0	0	0	1
45°	0	0	0	1	0	0	1
90°	0	0	0	0	1	0	1
180°	0	0	0	0	0	1	1
355°	1	1	1	1	1	1	1

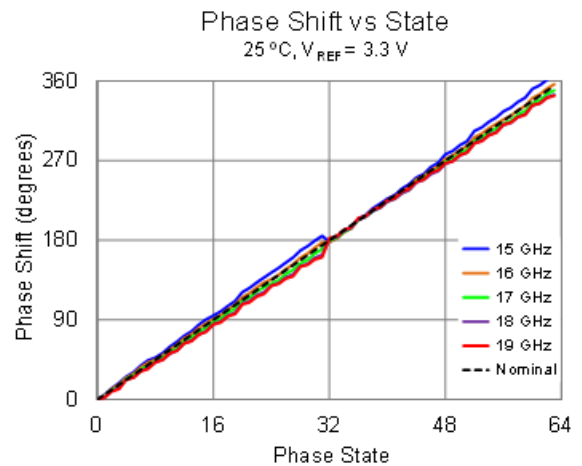
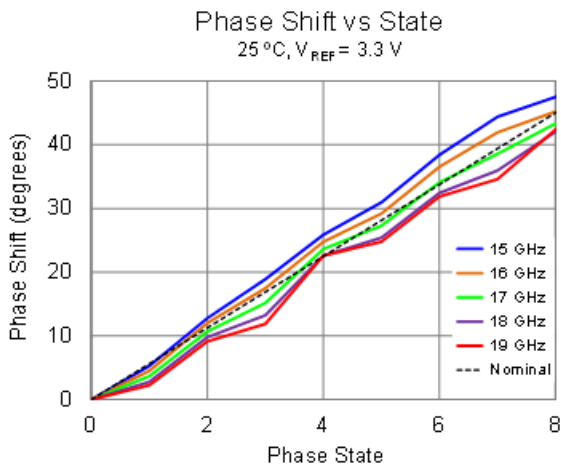
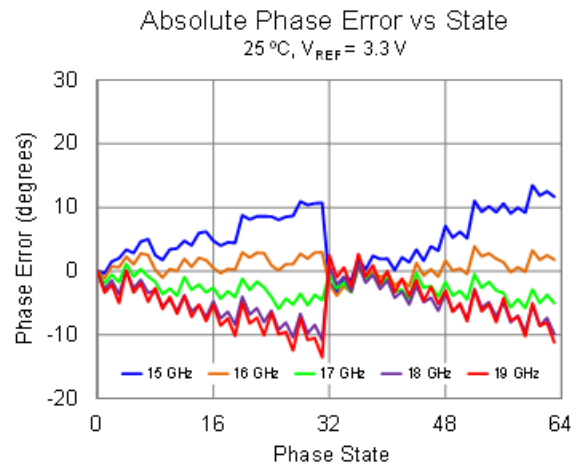
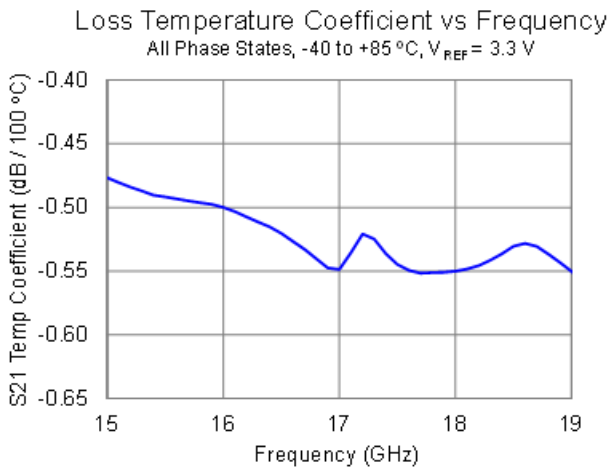
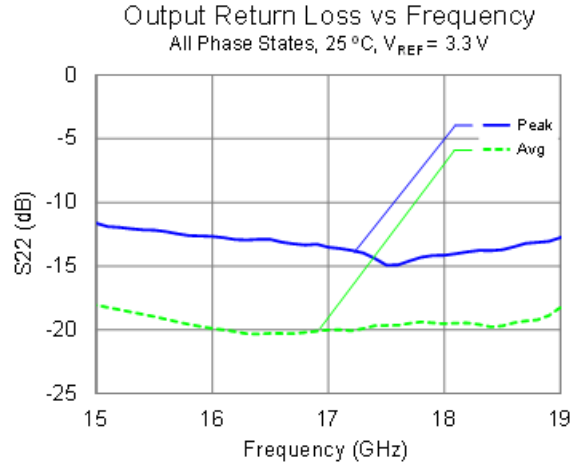
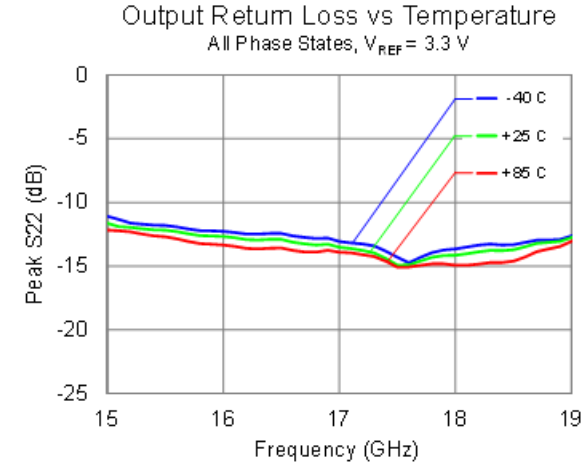
Performance Plots – Small Signal

Test conditions unless otherwise noted: 3.3 V, 25 °C



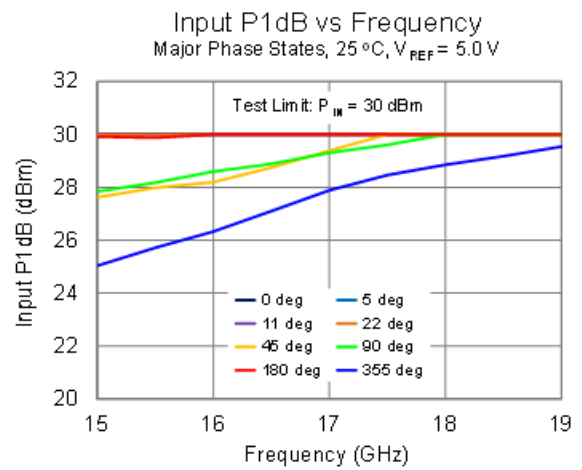
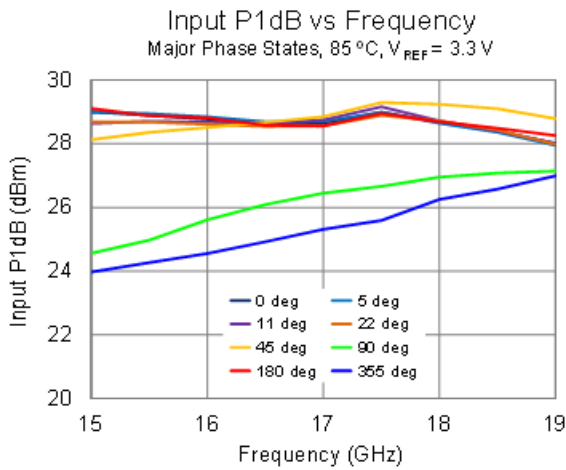
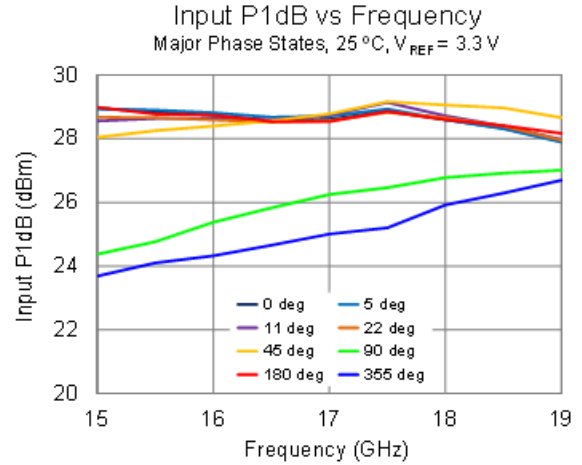
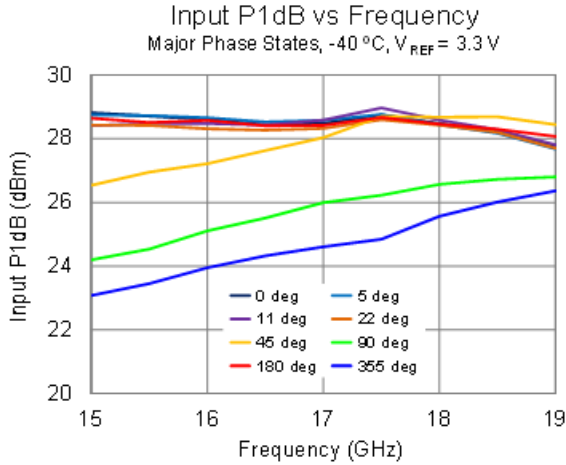
Performance Plots – Small Signal (Cont.)

Test conditions unless otherwise noted: 3.3 V, 25 °C



Performance Plots – Large Signal

Test conditions unless otherwise noted: 3.3 V, 25 °C



Thermal and Reliability Information

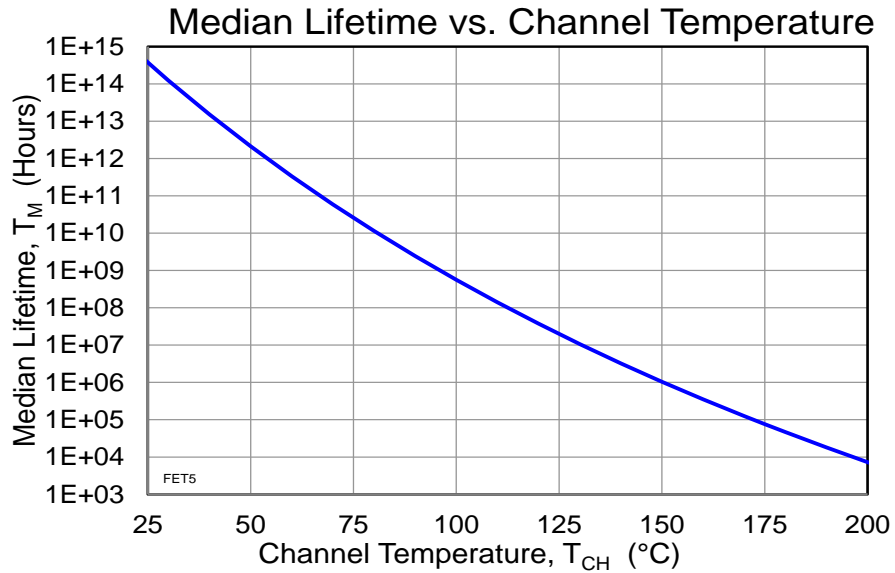
Parameter	Test Conditions	Value	Units
Channel Temperature (T_{CH})	$T_{BASEPLATE} = 85^{\circ}C$	85	$^{\circ}C$
Median Lifetime (T_M)		5.2E+9	Hrs

Notes:

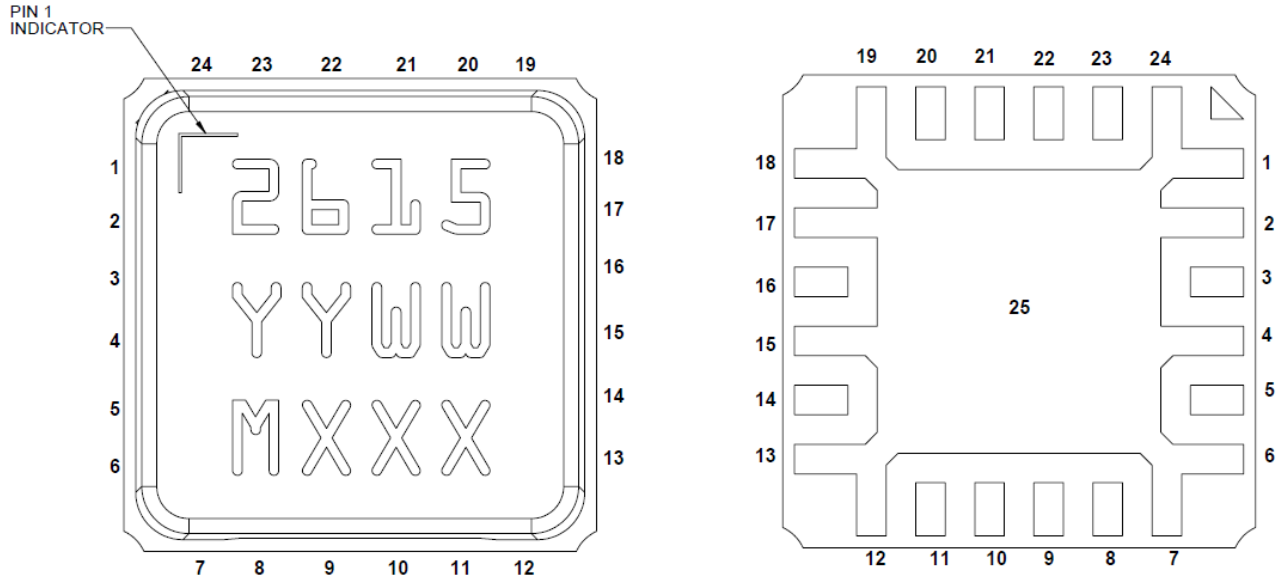
- Under normal (lifetime) operating conditions, self-heating is not a significant contributor to channel temperature.

Median Lifetime

Test Conditions: 6.0 V; Failure Criterion = 10% reduction in I_{DQ_MAX}

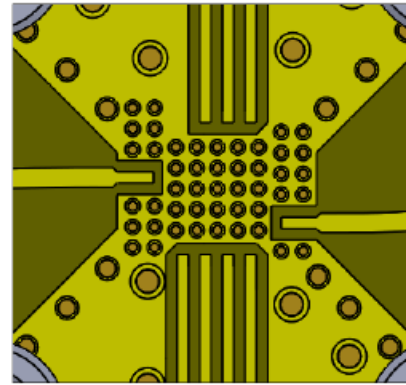
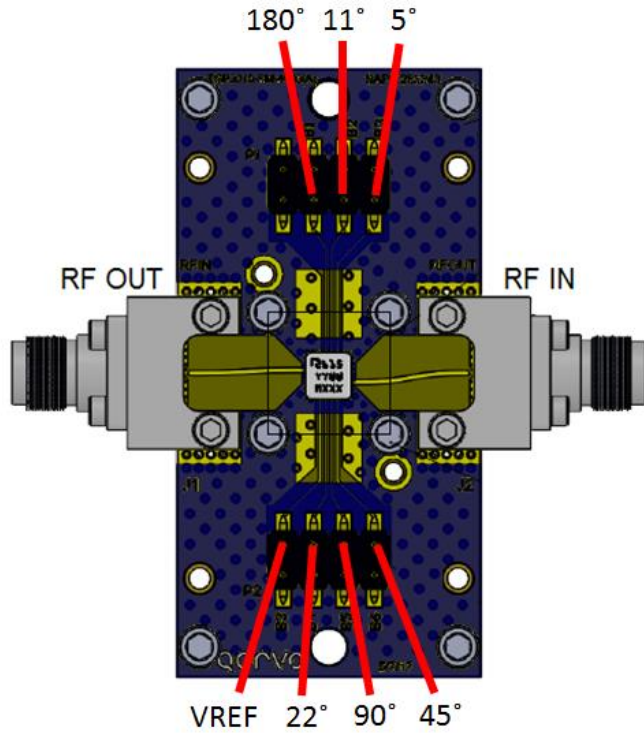


Pin Description



Pin No.	Symbol	Description
1, 2, 4, 6, 7, 12, 13, 15, 17-19, 24	GND	Internal grounding and shielding, must be grounded on PCB
3	RF OUT	RF Output, 50 Ω , DC-Blocked
5, 16, 23	NC	No Connection, Pin Not Used
8	V _{REF}	Reference Voltage for Logic "1" (Nominal 3.3 V)
9	22°	22° Bit Control
10	90°	90° Bit Control
11	45°	45° Bit Control
14	RF IN	RF Input, 50 Ω , DC-Blocked
20	5°	5° Bit Control
21	11°	11° Bit Control
22	180°	180° Bit Control
25 (Slug)	GND	Backside Paddle; multiple vias should be used on PCB to minimize inductance and thermal resistance

Evaluation Board (EVB) Layout Assembly



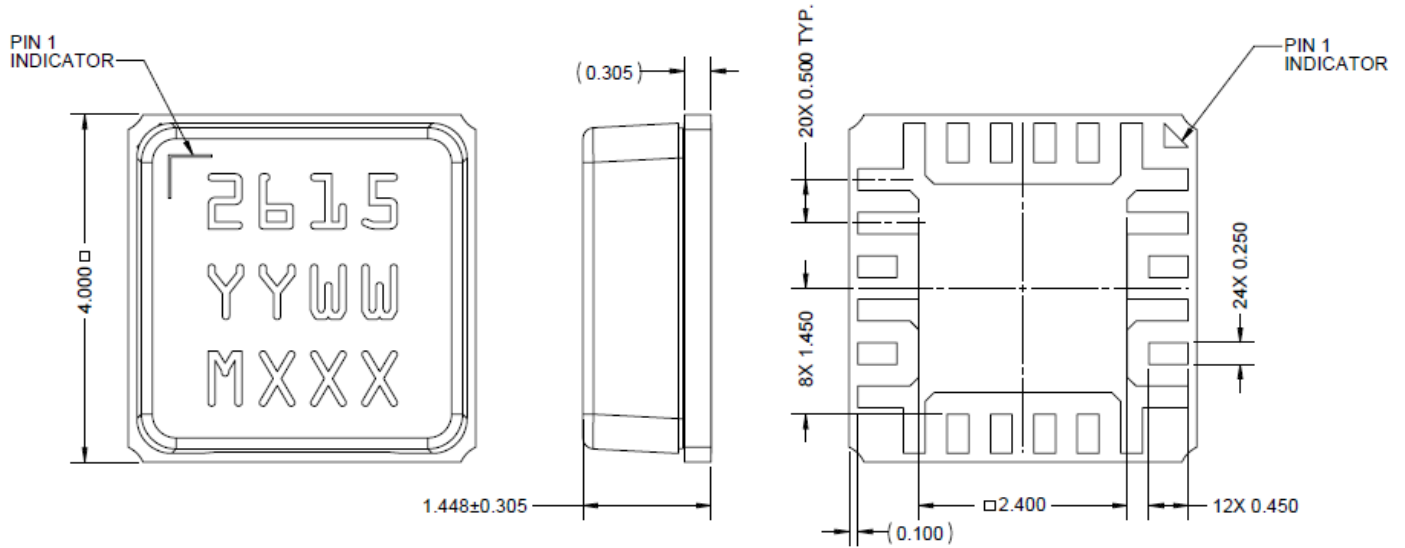
VIA PATTERN

RF layer is 0.008" thick Rogers RO4003C. Metal layers are 0.5-oz copper. Microstrip 50 Ω line width is 0.050". The microstrip line taper at the connector interface is optimized for the Southwest Microwave end-launch connector 1092-01A-5.

Ground / thermal vias under the DUT are critical for the proper performance of this device. The PCB shown herein utilizes copper filled vias (8 mils diameter) under the DUT.

The pad pattern shown has been developed and tested for optimized assembly at Qorvo. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from company to company careful process development is recommended.

Mechanical Information



NOTES:

1. PACKAGE BASE: CERAMIC
2. PACKAGE LID: PLASTIC
3. ALL METALIZED FEATURES ARE GOLD PLATED
4. THE PART IS EPOXY SEALED
5. PART MARKING:
 2615: PART NUMBER
 YY: PART ASSEMBLY YEAR
 WW: PART ASSEMBLY WEEK
 MXXX: BATCH ID

Assembly Notes

Compatible with both lead-free (260°C peak reflow temp.) and tin/lead (245°C peak reflow temp.) soldering processes.

This package is air-cavity and non-hermetic, and therefore cannot be subjected to aqueous washing. The use of no-clean solder to avoid washing after soldering is highly recommended.

Solder rework not recommended.

Contact plating: Ni-Au.

Recommended Soldering Temperature Profile

